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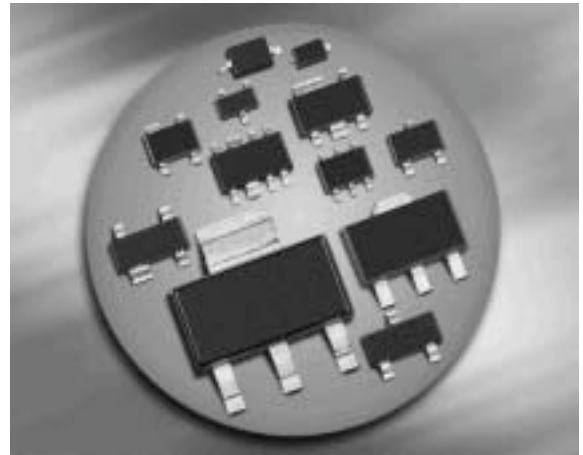
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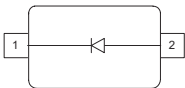


Silicon Schottky Diode

- High current rectifier Schottky diode with extreme low V_F drop (typ. 0.12V at $I_F = 10\text{mA}$)
- For power supply applications
- For clamping and protection in low voltage applications
- For detection and step-up-conversion
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



BAT60A



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Configuration	Marking
BAT60A	SOD323	single	white/3

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage ²⁾	V_R	10	V
Forward current	I_F	3	A
Non-repetitive peak surge forward current ($t \leq 10\text{ms}$)	I_{FSM}	5	
Total power dissipation $T_S \leq 28^\circ\text{C}$	P_{tot}	1350	mW
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 85	
Storage temperature	T_{stg}	-55 ... 150	

¹Pb-containing package may be available upon special request

²For $T_A > 25^\circ\text{C}$ the derating of V_R has to be considered. Please refer to curve Permissible reverse voltage.

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 90	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Reverse current ²⁾	I_R				mA
$V_R = 5\text{ V}$		-	0.3	1	
$V_R = 8\text{ V}$		-	0.6	2.6	
$V_R = 5\text{ V}, T_A = 80^\circ\text{C}$		-	18	-	
Forward voltage ²⁾	V_F				V
$I_F = 10\text{ mA}$		0.1	0.12	0.15	
$I_F = 100\text{ mA}$		0.15	0.2	0.23	
$I_F = 1000\text{ mA}$		0.22	0.3	0.37	

AC Characteristics

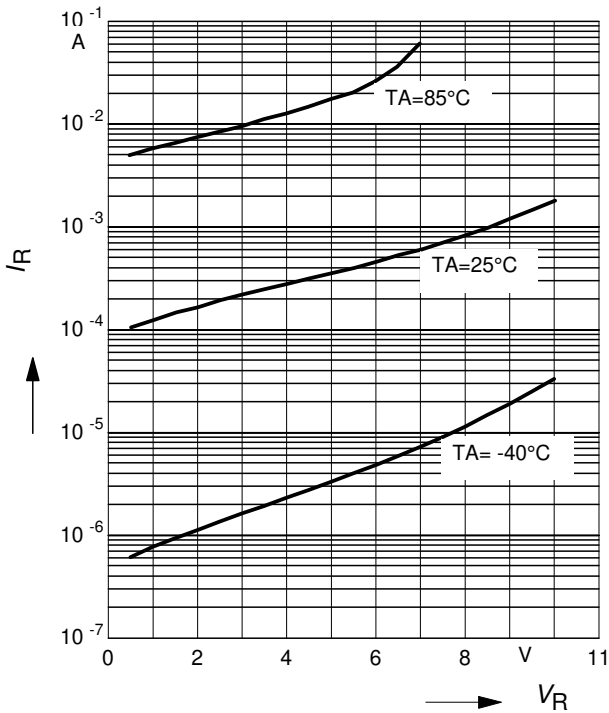
Diode capacitance	C_T	-	20	35	pF
$V_R = 5\text{ V}, f = 1\text{ MHz}$					

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

²Pulsed test: $t_p = 300\ \mu\text{s}; D = 0.01$

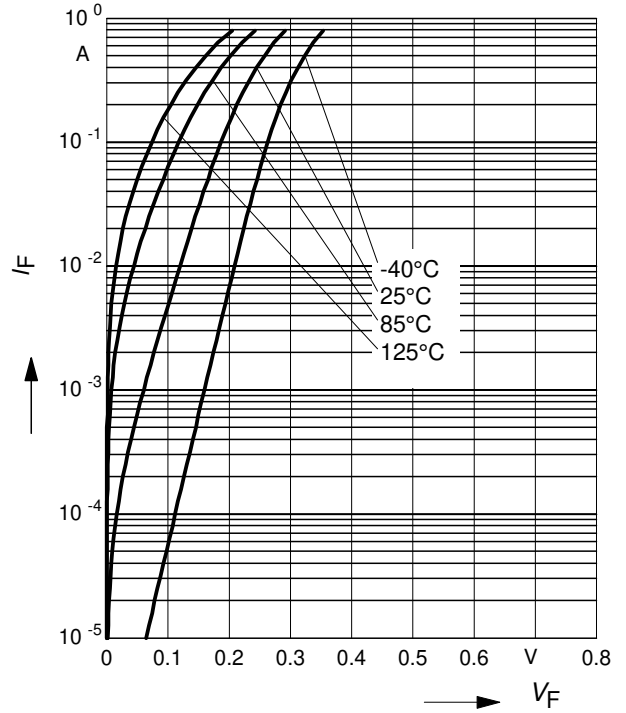
Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



Forward current $I_F = f(V_F)$

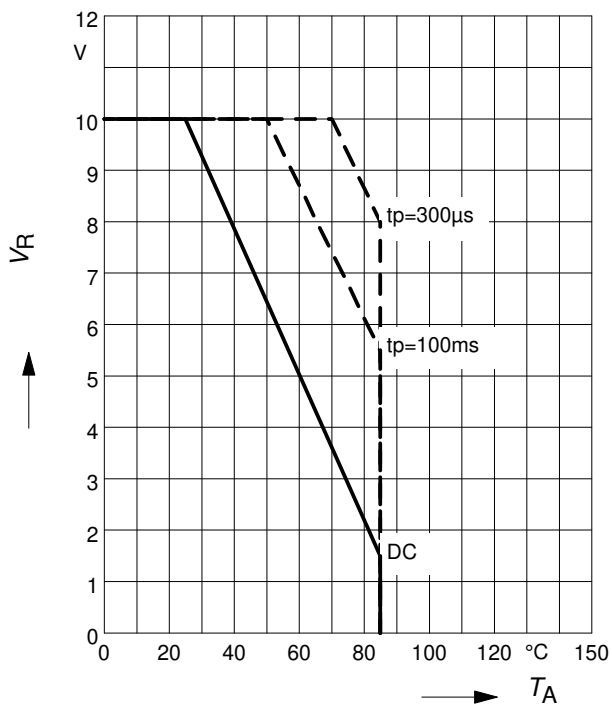
$T_A = \text{Parameter}$



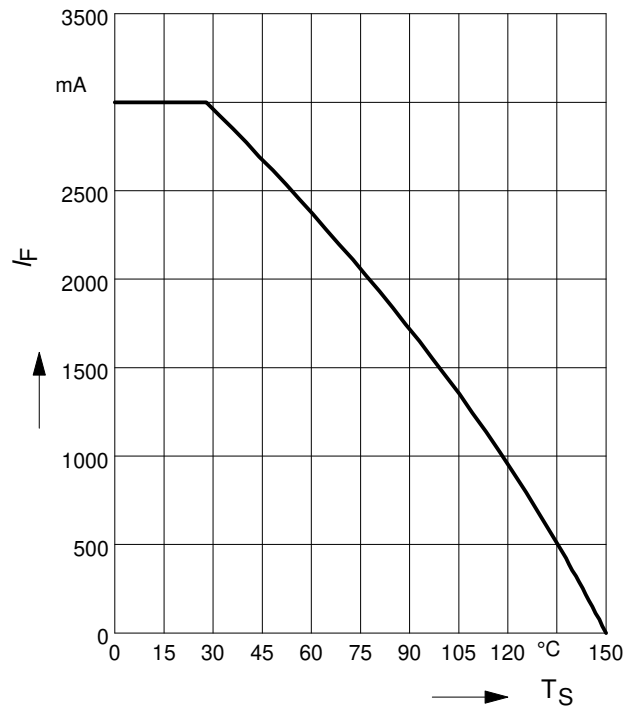
Permissible Reverse voltage $V_R = f(T_A)$

$t_p = \text{Parameter}$; duty cycle < 0.01

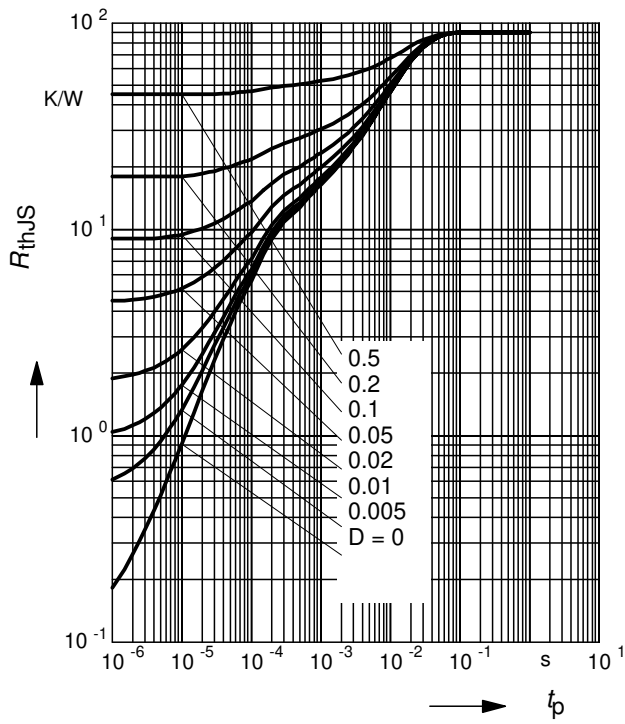
Device mounted on PCB with $R_{th} = 160 \text{ K/W}$



Forward current $I_F = f(T_S)$

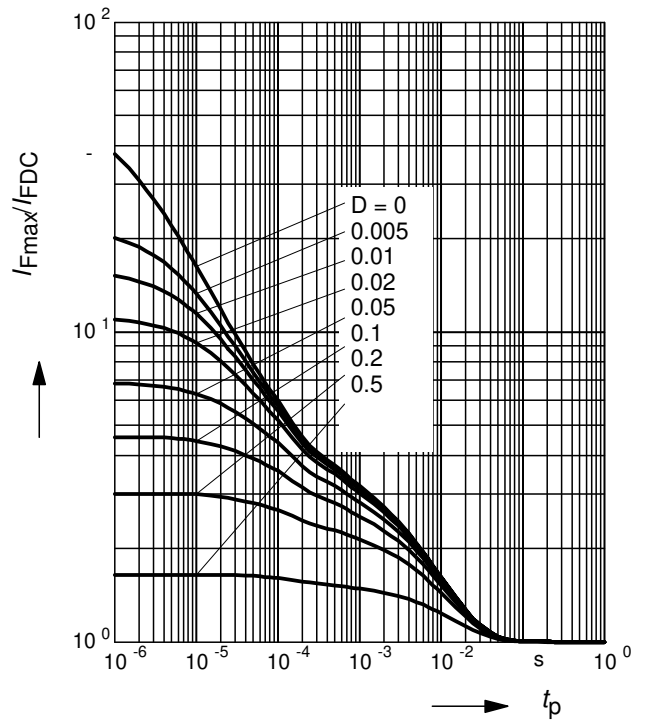


Permissible Puls Load $R_{thJS} = f(t_p)$

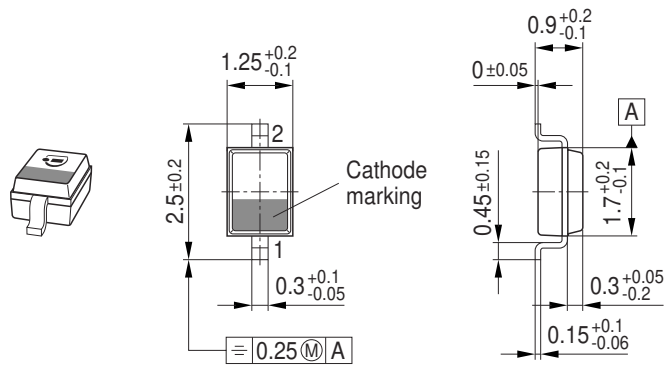


Permissible Pulse Load

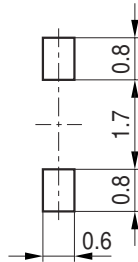
$I_{Fmax} / I_{FDC} = f(t_p)$



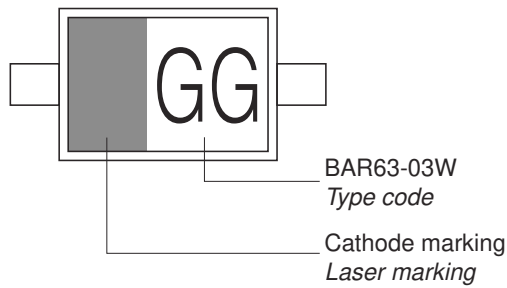
Package Outline



Foot Print

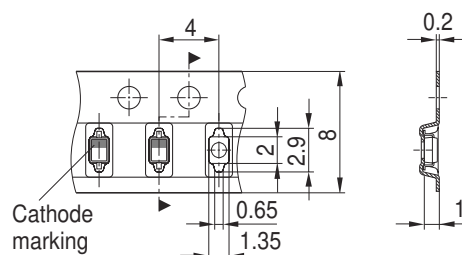


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



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